

MDTA Series

Flat Wire Molded Inductor

Size 5030



FEATURES

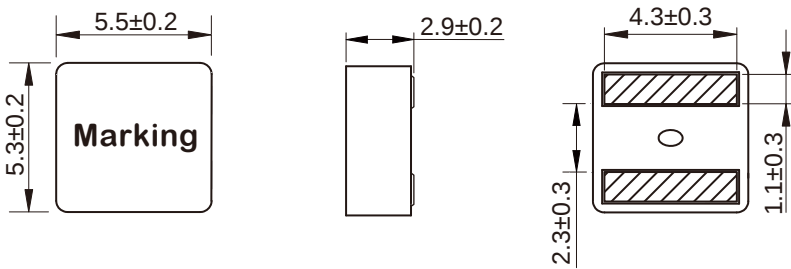
-
-
-
-
-
-

°C

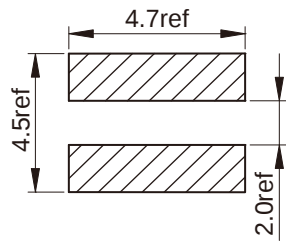
APPLICATION

-
-

Dimensions: [mm]



Land Pattern: [mm]



Electrical Properties:

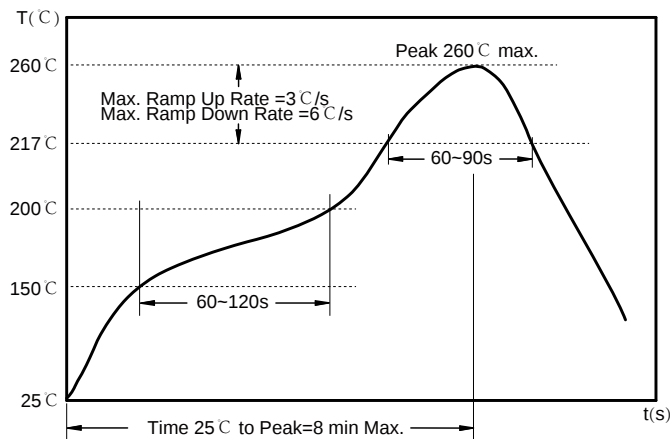
Part No	L@100KHz /0.1V	Tolerance	I _{SAT} Typ.	I _R		R _{DC} Max.
				20°C rise	40°C rise	

Saturation Current will cause L to drop approximately 30%
 Temperature Rise Current that causes the specified temperature rise from 25°C ambient.

Typical Electrical Characteristics:

	INDUCTANCE (	

Soldering Reflow:



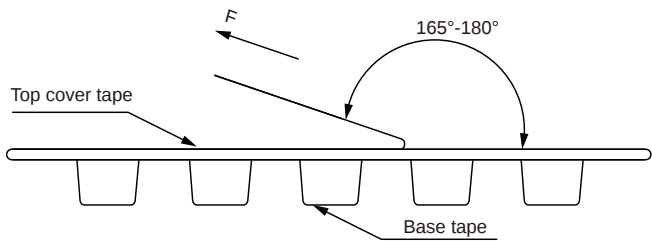
Preheat condition: $150 \sim 200^{\circ}\text{C} / 60 \sim 120 \text{ sec.}$
Allowed time above 217°C : 60~90 sec.
Max temperature: 260°C .
Max time at max temperature: 10 sec.
Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension :

Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDTA5030	6.0 ± 0.1	5.7 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	8.0 ± 0.1	16.0 ± 0.3	3.3 ± 0.1	1.75 ± 0.1	0.35 ± 0.05

Peel force of top cover tape:

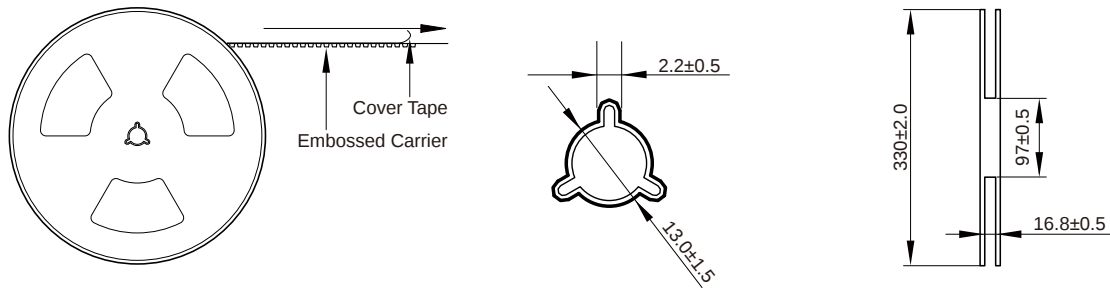


The peel force of top cover tape shall be between 0.1 to 1.3 N

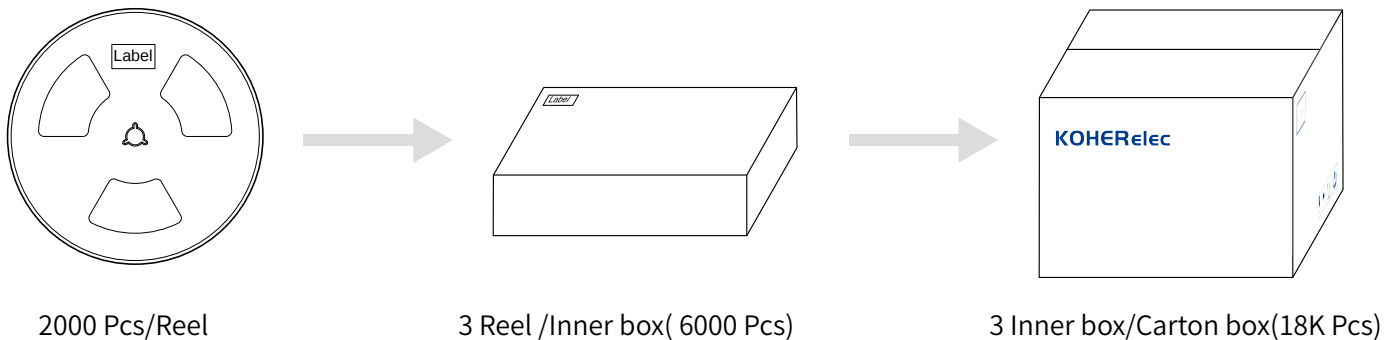
Product Marking:

Marking	Printing (Inductance)
---------	-----------------------

Reel Dimension: [mm]



Packaging Quantity:



Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max). If the storage period elapses, the soldering of the terminal electrodes may deteriorate. The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does. As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.